LINEAR TECHNOLOGY MATERIALS DECLARATION

LT1121AIS8-3.3#PBF		(Engineering Calculation)		SOIC		
(printed on: 7/16/2011 12:18:42 PM)					TOTAL MASS (g):	0.07281985
COMPONENT	VENDOR/	CONSTITUENT	CAS	CONSTITUENT	CONSTITUENT	CONSTITUENT
MATERIAL	INDUSTRY NAMES	NAME	NUMBER	MASS (g)	(PPM) OF MATERIAL	(PPM) OF TOTAL PKG.
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001703	1000000	23386.48
Die Coat	Dow Corning	Silicone	67762-90-7	0	0	0
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.023653	975000	324815.3
		Iron (Fe)	7439-89-6	0.000582	24000	7992.326
		Phosporus (P)	7723-14-0	7.00E-06	300	96.12764
		Zinc (Zn)	7440-66-6	1.70E-05	700	233.4528
		Nickel (Ni)	7440-02-0	0	0	0
		Silicon (Si)	7440-21-3	0	0	0
		Magnesium (Mg)	7439-95-4	0	0	0
		Tin (Sn)	7440-31-5	0	0	0
		Lead Frame Total:		0.024259	1000000	333137.2
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0
		Exter. Plating Sn	7440-31-5	0.001476852	1000000	20280.9
		External Plating Total:		0.001476852	1000000	20280.9
		Inter. Plating Ni	7440-02-0	0	0	0
		Inter. Plating Ag	7440-22-4	6.80E-05	1000000	933.8113
		Internal Plating Total:		6.80E-05	1000000	933.8113
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000617	750000	8472.964
		Tin (Sn)	7440-31-5	0	0	0
		Lead (Pb)	7439-92-1	0	0	0
		Silica (SiO2)	60676-86-0	0	0	0
		Metal Oxide		0	0	0
		Antimony (Sb)	7440-36-0	0	0	0
		Resin (EP)		0.000206	250000	2828.899
		Die Attach Total:		0.000823	1000000	11301.86
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.006657	150000	91417.38
		Bromine (Br)	40039-93-8	0	0	0
		Silica (SiO2)	60676-86-0	0.036392	820000	499753.8
		Antimony	1309-64-4	0	0	0
		Trioxide (Sb2O3)				
		Metal Hydroxid		0.00111	25000	15243.1
		Carbon Black (C)	1333-86-4	0.000222	5000	3048.619
		Encapsulation Total:		0.044381	1000000	609462.9
Bond Wire	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000109	1000000	1496.845
Estimated						
				TOTAL MASS (g):		0.07281985